

I CLAIM:

1. A water soluble hot melt blocking composition for contact lens manufacture, the composition comprising:
 - 5 (a) about 5 to 95 wt% of a water soluble polymer composition; and
 - (b) about 1 to about 50 wt% of a highly water soluble micronized salt comprising a sodium or potassium salt of a strong acid, the salt having a particle size of less than about 150 microns.
- 10 2. The composition of claim 1 wherein the salt comprises a sodium chloride, potassium chloride or mixtures thereof and the particle size of the salt is less than 90 microns.
- 15 3. The composition of claim 1 wherein the water-soluble polymer comprises a cellulosic polymer in an amount of about 15 to 75 wt.%.
4. The composition of claim 1 wherein the polymer comprises a poly(ethyleneglycol) in an amount of about 15 to 75 wt.%.
- 20 5. The composition of claim 1 wherein the water-soluble polymer comprises a poly (vinyl pyrrolidone) in an amount of about 15 to 75 wt.%.
6. The composition of claim 1 wherein the particle size is about 20 to 80 microns.
- 25 7. The composition of claim 1 additionally comprising a surfactant.
8. The composition of claim 1 wherein the composition comprises about 10-50 wt% of a hydroxy substituted organic compound.
- 30 9. The composition of claim 7 wherein the hydroxy substituted organic compound comprises hydroxywax.

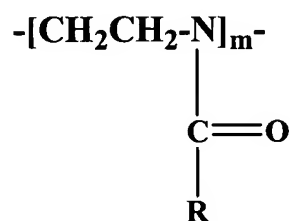
10. A water-soluble hot melt blocking composition for contact lens manufacture, the composition comprising:

- 5 (a) about 25-50 wt% of a water soluble alkyl substituted polyethyleneimine polymer; and
(c) about 5 to about 50 wt% of a water soluble sodium or potassium salt of a strong acid.

10 11. The composition of claim 10 additionally comprising about 10-50 wt% of a hydroxy substituted organic compound comprising a hydroxywax having hydroxy number of greater than 150.

12. The composition of claim 10 wherein the alkyl substituted polyethyleneimine polymer comprises a compound of the formula:

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wherein R is a C₁₋₅ alkyl, m is about 50-10,000.

13. The composition of claim 10 wherein there is about 25 to 40 wt% of the water soluble polymer, about 15 to 45 wt% of a hydroxywax and about 15 to 45 wt% of a water soluble micronized sodium chloride or potassium chloride salt.

14. The composition of claim 10 more in the particle size is less than about 150 microns.

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15. The composition of claim 10 additionally comprising a surfactant.

16. The composition of claim 10 wherein the composition comprises about 10-50 wt% of a hydroxy substituted organic compound.

5 17. The composition of claim 16 wherein the hydroxy substituted organic compound comprises hydroxywax.

18. A water soluble hot melt blocking composition for contact lens manufacture, the composition comprising:

- 10 (a) about 5 - 90 wt% of a water soluble polymer composition;
(b) about 1 - 50 wt% of a hydroxy substituted organic compound; and
(c) about 1 - 50 wt% of an inorganic filler material;

wherein the components are blended such that the material is a structural solid at a temperature of less than about 130°F and wherein the material is substantially melt form at a temperature greater than 140°F.

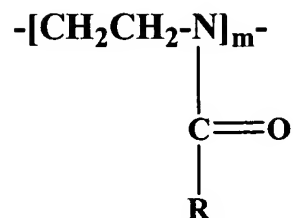
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19. The composition of claim 18 wherein the composition is a solid at less than 120°F.

20 20. The composition of claim 18 wherein the composition is a melt at a temperature greater than 165°F.

21. The composition of claim 18 wherein the hydroxy substituted organic compound comprises about 5-50 wt% of a hydroxy wax.

25 22. The composition of claim 18 wherein the water-soluble polymer comprises an alkyl substituted polyethyleneimine polymer comprising a compound of the formula:



wherein R is a C₁₋₅ alkyl, m is about 50-10,000 and is present in an amount of about 15 to 75 wt.%.

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23. The composition of claim 18 wherein the inorganic filler comprises a sodium or potassium salt of a strong acid.

24. The composition of claim 18 wherein the water-soluble polymer
10 comprises a polyethyl oxazoline polymer having a molecular weight of about 10,000 to 500,000 and is present in an amount of about 15 to 45 wt.%.

25. The composition of claim 18 wherein the inorganic filler comprises a
particle size less than about 150 microns.

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26. The composition of claim 18 wherein the hydroxy substituted organic
compound has a hydroxy number of greater than 150.

27. The composition of claim 18 wherein the composition comprises a
20 surfactant.